

The Office Action objects to claim 11 under 37 C.F.R. §1.75(c) as failing to further limit the subject matter of a previous claim. Claim 11 has been canceled, and therefore withdrawal of the objection under 37 C.F.R. §1.75(c) is respectfully requested.

The Office Action rejects claims 1-4 and 6-12 under 35 U.S.C. §102(b) as being anticipated by Thompson (U.S. Patent No. 5,293,067) or in the alternative under 35 U.S.C. §103(a) as being obvious over Thompson or in the alternative under 35 U.S.C. §103(a) as being obvious over Thompson in view of Rostoker (U.S. Patent No. 5,767,580). Applicant respectfully traverses the rejections.

Prior to addressing the rejections above, claims 2, 8 and 11 have been canceled and therefore are moot to the rejection. However, the features of claims 2 and 8 have been incorporated into independent claims 1 and 7 respectively and clarified, and therefore the rejection with respect to claims 2 and 8 are equally applicable to independent claims 1 and 7 respectively.

Applicant respectfully submits that Thompson fails to disclose or suggest a substrate for semiconductor apparatus, where the substrate main body includes a plurality of through-holes internal surfaces connected to respective leads, such that as the substrate main body is cut along predetermined through-holes, remaining through-holes of the substrate main body define the conduction sections, as recited in independent claim 1, and similarly recited in independent claim 7.

Thompson discloses an integrated circuit chip carrier assembly including a semiconductor device 10 carried to a circuitry pattern 18 on a first side of a circuit carrying substrate 16. As set forth in col. 2, lines 61-65, for example, the substrate 16 also contains other circuitry 20 that interconnects pad to the conductive thru-holes of vias 22 in the substrate. However, Thompson fails to disclose or suggest the substrate main body where as the substrate main body is cut along predetermined through-holes, remaining through-holes

of the substrate main body define the conduction sections. In fact, Thompson makes no mention that the substrate main body is cut at all.

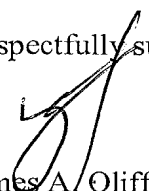
Rostoker fails to cure the above noted deficiencies of Thompson. Rostoker discloses on Fig. 3a that the bump pad is of a rectangular ring shape. However, similar to Thompson, Rostoker fails to disclose or suggest the substrate main body where as the substrate main body is cut along predetermined through-holes, remaining through-holes of the substrate main body define the conduction sections, as recited in independent claim 1, and similarly recited in independent claim 7.

Accordingly, Applicant submits that independent claims 1 and 7 define patentable subject matter. Claims 3-4 and 6 depend from independent claim 1, and claims 9-12 depend from independent claim 7, and therefore so define patentable subject matter. Accordingly, Applicant requests that objections, and rejections under 35 U.S.C. §102(b) and 35 U.S.C. §103(a) be withdrawn.

In view of the foregoing amendments and remarks, Applicant submits that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1, 3-4, 6, 7 and 9-12 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in better condition for allowance, the Examiner is invited to contact Applicant's undersigned attorney at the telephone number listed below.

Respectfully submitted,


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Date: September 17, 2002

Attachment:
Appendix

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DEPOSIT ACCOUNT USE AUTHORIZATION Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461
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